Technical Bulletin SFHPI-2-99

Floor Suspended of Spring and/or Movement

To help minimize de-bonding or stress cracking of SKIMFLOW® HPI underlayment, the following procedures can be employed:

1. Ensure all loose boards are nailed or screwed securely.
2. Remove all foreign matter such as dirt, oil, paint, varnish or any contaminant, which may inhibit a satisfactory bond. A commercial drum sander may be required for a complete removal of contaminates.
3. Fill all plywood seams, gaps, holes or voids, which may allow SKIMFLOW® HPI to escape with Dependable WHITE SKIMCOAT™.
4. Prime entire floor surface using a soft bristle broom or long handled paint roller with PRIMER SL™. NOTE: Primed areas left exposed after 24 hours may require a second application of primer.
5. Install 3.4 galvanized expanded diamond lath mesh, fastening with galvanized staples every 6” at seams and throughout the entire field. Overlay adjacent pieces of lathe 1”.
6. Apply SKIMFLOW® HPI to a depth a minimum of 1/8” above diamond lath mesh.

If you have any questions or comments with respect to this technical bulletin, please contact technical service at Dependable, LLC at 1-800-227-3434.